Electronic Patent Application Fee Transmittal								
Application Number:	09538684							
Filing Date:	30-Mar-2000							
Title of Invention:	Varied-thickness heat sink for integrated circuit (ic) package							
First Named Inventor/Applicant Name:	Larry D. Kinsman							
Filer:	James R. Duzan/Leta Howard							
Attorney Docket Number:	3056.1US (96-803.1)							
Filed as Large Entity								
Utility Filing Fees								
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:								
Miscellaneous-Filing:								
Petition:								
Patent-Appeals-and-Interference:								
Post-Allowance-and-Post-Issuance:								
Extension-of-Time:								

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
	Tota	O (\$)	180	